

# CMOS Dual 'D'-Type Flip-Flop

High-Voltage Types (20-Volt Rating)

■ CD4013B consists of two identical, independent data-type flip-flops. Each flip-flop has independent data, set, reset, and clock inputs and Q and  $\bar{Q}$  outputs. These devices can be used for shift register applications, and, by connecting  $\bar{Q}$  output to the data input, for counter and toggle applications. The logic level present at the D input is transferred to the Q output during the positive-going transition of the clock pulse. Setting or resetting is independent of the clock and is accomplished by a high level on the set or reset line, respectively.

The CD4013B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

### RECOMMENDED OPERATING CONDITIONS

At  $T_A = 25^\circ\text{C}$ , Except as Noted. For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	$V_{DD}$ (V)	LIMITS		UNITS
		MIN.	MAX.	
Supply-Voltage Range (For $T_A =$ Full Package Temperature Range)	—	3	18	V
Data Setup Time $t_S$	5	40	—	ns
	10	20	—	
Clock Pulse Width $t_W$	5	140	—	ns
	10	60	—	
Clock Input Frequency $f_{CL}$	5	—	3.5	MHz
	10	dc	8	
Clock Rise or Fall Time $t_{rCL}, t_{fCL}$	5	—	500	$\mu\text{s}$
	10	—	30	
Set or Reset Pulse Width $t_W$	5	180	—	ns
	10	80	—	
	15	50	—	

\*If more than one unit is cascaded in a parallel clocked operation,  $t_{rCL}$  should be made less than or equal to the sum of the fixed propagation delay time at 15 pF and the transition time of the output driving stage for the estimated capacitive load.

# CD4013B Types

### Features:

- Set-Reset capability
- Static flip-flop operation — retains state indefinitely with clock level either "high" or "low"
- Medium-speed operation — 16 MHz (typ.) clock toggle rate at 10V
- Standardized symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of  $1 \mu\text{A}$  at 18 V over full package temperature range; 100 nA at 18 V and  $25^\circ\text{C}$
- Noise margin (over full package temperature range):  
1 V at  $V_{DD}=5\text{ V}$   
2 V at  $V_{DD}=10\text{ V}$   
2.5 V at  $V_{DD}=15\text{ V}$
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

### Applications:

- Registers, counters, control circuits

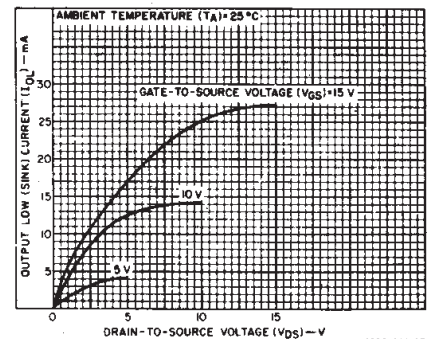
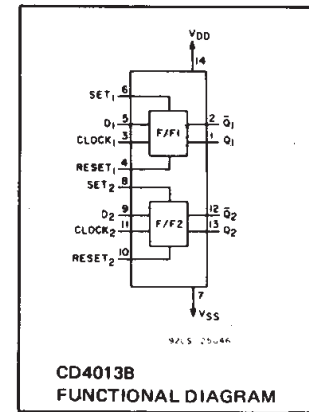


Fig. 1 — Typical output low (sink) current characteristics.

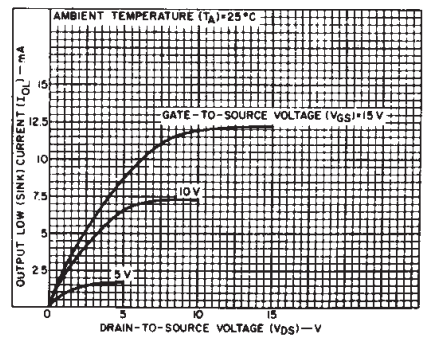


Fig. 2 — Minimum output low (sink) current characteristics.

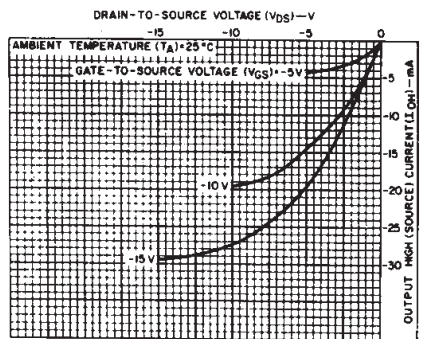


Fig. 3 — Typical output high (source) current characteristics.

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# CD4013B Types

## STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current I <sub>DD</sub> Max.	—	0.5	5	1	1	30	30	—	0.02	1	μA
	—	0.10	10	2	2	60	60	—	0.02	2	
	—	0.15	15	4	4	120	120	—	0.02	4	
	—	0.20	20	20	20	600	600	—	0.04	20	
Output Low (Sink) Current, I <sub>OL</sub> Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	—	
	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
Output High (Source) Current, I <sub>OH</sub> Min.	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
	—	0.5	5	—	—	—	—	—	—	—	
	—	0.10	10	—	—	—	—	—	—	—	
Output Voltage: Low-Level, V <sub>OL</sub> Max.	—	0.5	5	—	—	—	—	—	—	—	V
	—	0.10	10	—	—	—	—	—	—	—	
	—	0.15	15	—	—	—	—	—	—	—	
Output Voltage: High-Level, V <sub>OH</sub> Min.	—	0.5	5	—	—	—	—	—	—	—	V
	—	0.10	10	—	—	—	—	—	—	—	
	—	0.15	15	—	—	—	—	—	—	—	
Input Low Voltage, V <sub>IL</sub> Max.	0.5, 4.5	—	5	—	—	—	—	—	—	—	V
	1.9	—	10	—	—	—	—	—	—	—	
	1.5, 13.5	—	15	—	—	—	—	—	—	—	
Input High Voltage, V <sub>IH</sub> Min.	0.5, 4.5	—	5	—	—	—	—	—	—	—	V
	1.9	—	10	—	—	—	—	—	—	—	
	1.5, 13.5	—	15	—	—	—	—	—	—	—	
Input Current, I <sub>IN</sub> Max.	—	0.18	18	±0.1	±0.1	±1	±1	—	±10 <sup>-5</sup>	±0.1	μA

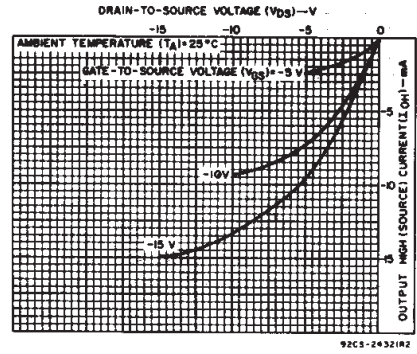


Fig. 4 — Minimum output high (source) current characteristics.

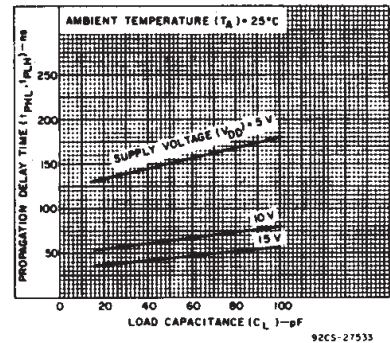


Fig. 5 — Typical propagation delay time vs. load capacitance (CLOCK or SET to Q, CLOCK or RESET to Q).

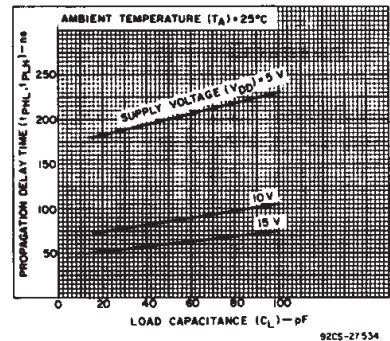


Fig. 6 — Typical propagation delay time vs. load capacitance (SET to Q or RESET to Q).

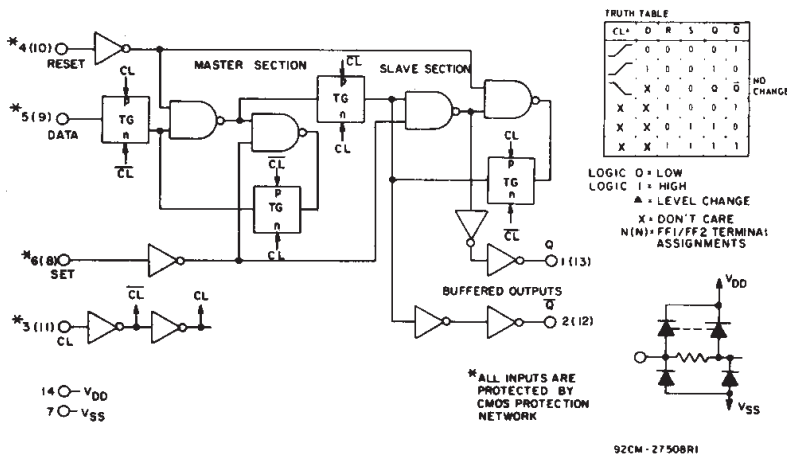


Fig. 7 — Logic diagram and truth table for CD4013B (one of two identical flip-flops).

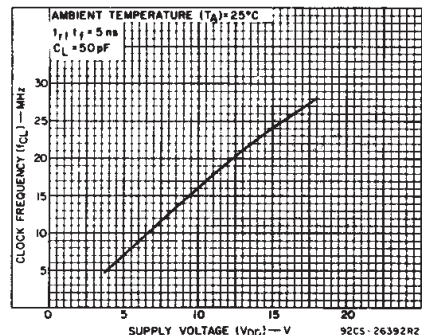


Fig. 8 — Typical maximum clock frequency vs. supply voltage.

# CD4013B Types

## MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )		-0.5V to +20V
Voltages referenced to $V_{SS}$ Terminal		
INPUT VOLTAGE RANGE, ALL INPUTS		-0.5V to $V_{DD}$ +0.5V
DC INPUT CURRENT, ANY ONE INPUT		$\pm 10$ mA
POWER DISSIPATION PER PACKAGE ( $P_D$ ):		
For $T_A = -55^\circ\text{C}$ to $+100^\circ\text{C}$		500mW
For $T_A = +100^\circ\text{C}$ to $+125^\circ\text{C}$		Derate Linearly at 12mW/ $^\circ\text{C}$ to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR		
FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$		100mW
OPERATING-TEMPERATURE RANGE ( $T_A$ )		$-55^\circ\text{C}$ to $+125^\circ\text{C}$
STORAGE TEMPERATURE RANGE ( $T_{stg}$ )		$-65^\circ\text{C}$ to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):		
At distance $1/16 \pm 1/32$ inch ( $1.59 \pm 0.79$ mm) from case for 10s max		$+265^\circ\text{C}$

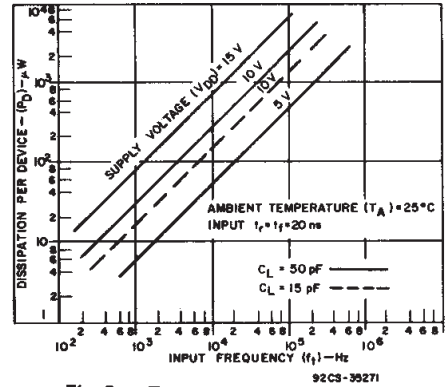


Fig. 9 – Typical power dissipation vs. frequency.

## DYNAMIC ELECTRICAL CHARACTERISTICS

At  $T_A = 25^\circ\text{C}$ ; Input  $t_r, t_f = 20$  ns,  $C_L = 50$  pF,  $R_L = 20$  k $\Omega$

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS
		$V_{DD}$ (V)	MIN.	TYP.	
Propagation Delay Time: Clock to Q or $\bar{Q}$ Outputs $t_{PHL}, t_{PLH}$	5	—	150	300	ns
	10	—	65	130	
	15	—	45	90	
Set to Q or Reset to $\bar{Q}$ $t_{PLH}$	5	—	150	300	ns
	10	—	65	130	
	15	—	45	90	
Set to $\bar{Q}$ or Reset to Q $t_{PHL}$	5	—	200	400	ns
	10	—	85	170	
	15	—	60	120	
Transition Time $t_{THL}, t_{TLH}$	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Maximum Clock Input Frequency# $f_{CL}$	5	3.5	7	—	MHz
	10	8	16	—	
	15	12	24	—	
Minimum Clock Pulse Width $t_w$	5	—	70	140	ns
	10	—	30	60	
	15	—	20	40	
Minimum Set or Reset Pulse Width $t_w$	5	—	90	180	ns
	10	—	40	80	
	15	—	25	50	
Minimum Data Setup Time $t_s$	5	—	20	40	ns
	10	—	10	20	
	15	—	7	15	
Minimum Data Hold Time $t_H$	5	—	2	5	ns
	10	—	2	5	
	15	—	2	5	
Clock Input Rise or Fall Time $t_{rCL}, t_{fCL}$	5	—	—	500	$\mu\text{s}$
	10	—	—	30	
	15	—	—	6	
Input Capacitance $C_{IN}$	Any Input	—	5	7.5	pF

#Input  $t_r, t_f = 5$  ns.

## TEST CIRCUITS

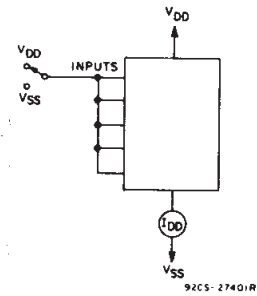


Fig. 10 – Quiescent device current.

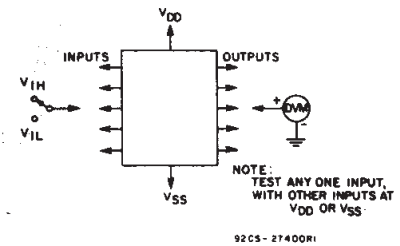


Fig. 11 – Input voltage.

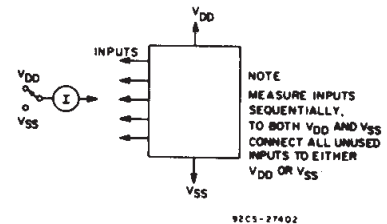


Fig. 12 – Input current.

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## CD4013B Types

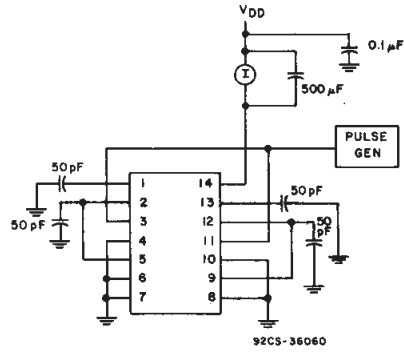
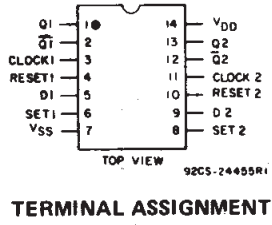
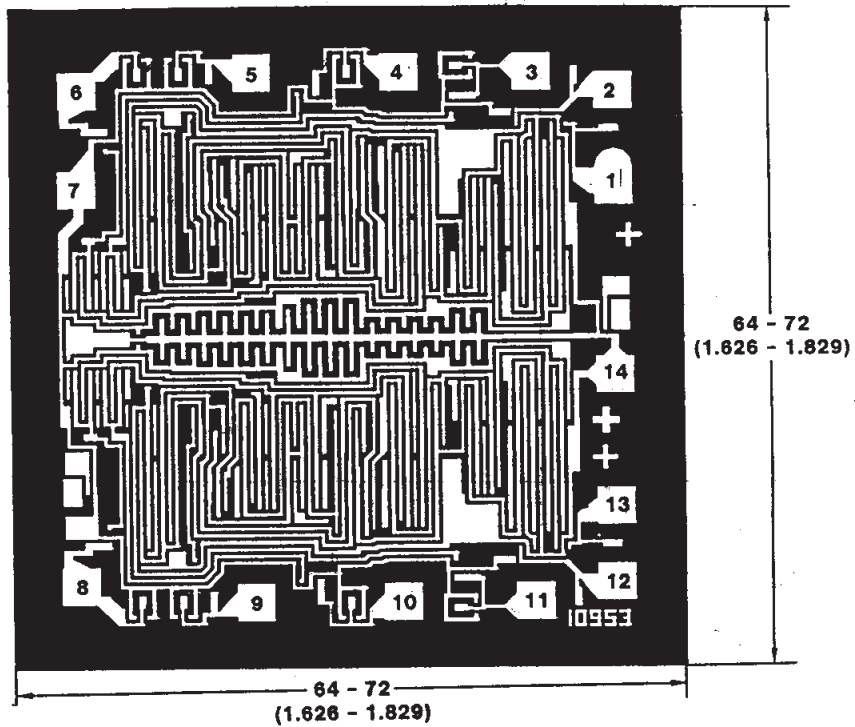


Fig. 13—Dynamic power dissipation test circuit.

### DIMENSIONS AND PAD LAYOUT FOR CD4013BH



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).

# J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



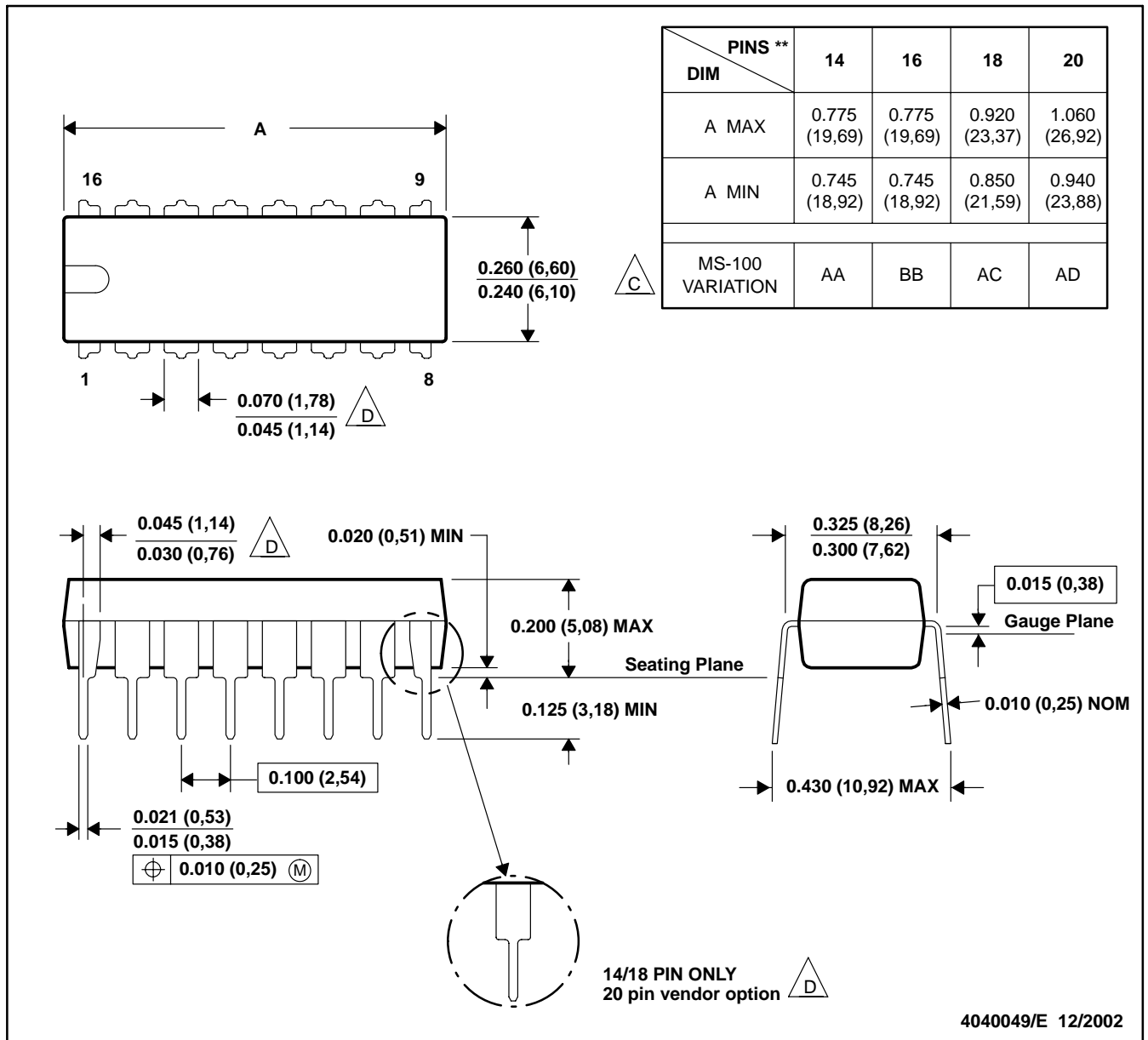
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 D The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MS-012

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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